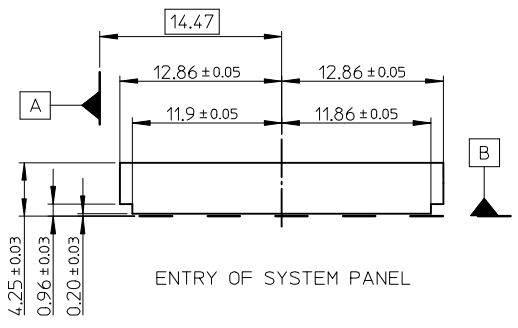
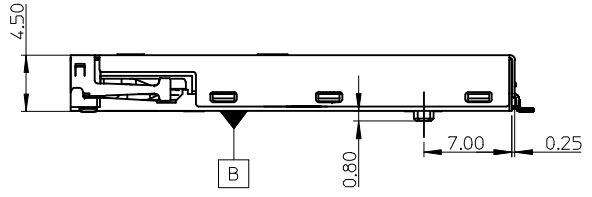
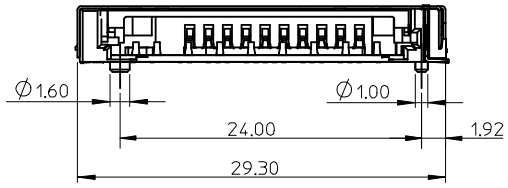


NOTE:

1.MATERIALS:  
 HOUSING: HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94 V-0.  
 TERMINAL : NAIL AND SWITCH: COPPER ALLOY.  
 METAL SHELL: STAINLESS STEEL

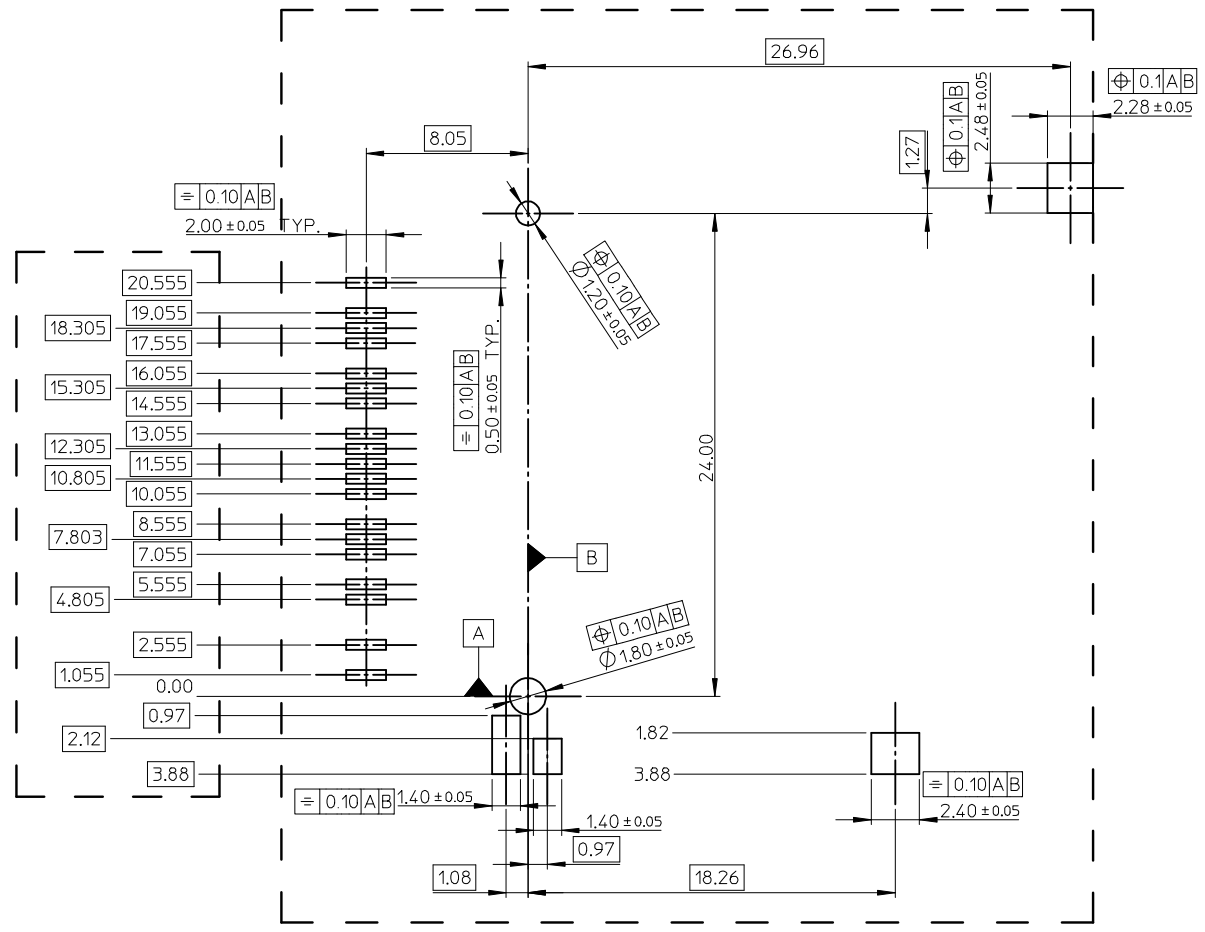
2.FINISH:  
 TERMINAL: NICKEL OVERALL UNDERPLATING, THICKNESS : 1.27 MICROMETER MIN. SELECTIVE GOLD ON CONTACT AREA, THICKNESS : 0.2 MICROMETER MIN. TIN ALLOY ON SOLDER AREA. THICKNESS : 3 MICROMETER MIN.  
 SWITCH: NICKEL OVERALL UNDERPLATING, THICKNESS : 1.27 MICROMETER MIN. SELECTIVE GOLD ON CONTACT AREA, THICKNESS : 0.05 MICROMETER MIN. TIN ALLOY ON SOLDER AREA. THICKNESS : 3 MICROMETER MIN.  
 NAIL: NICKEL OVERALL UNDERPLATING, THICKNESS : 1.27 MICROMETER MIN. TIN ALLOY ,THICKNESS : 3 MICROMETER MIN. ON SOLDER AREA

3.COPLANARITY: 0.15 MAX.  
 4.PRODUCT SPECIFICATION: PS-48000-001  
 5.PACKAGING: PK-48000-001  
 6.PRODUCT COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.



ENTRY OF SYSTEM PANEL

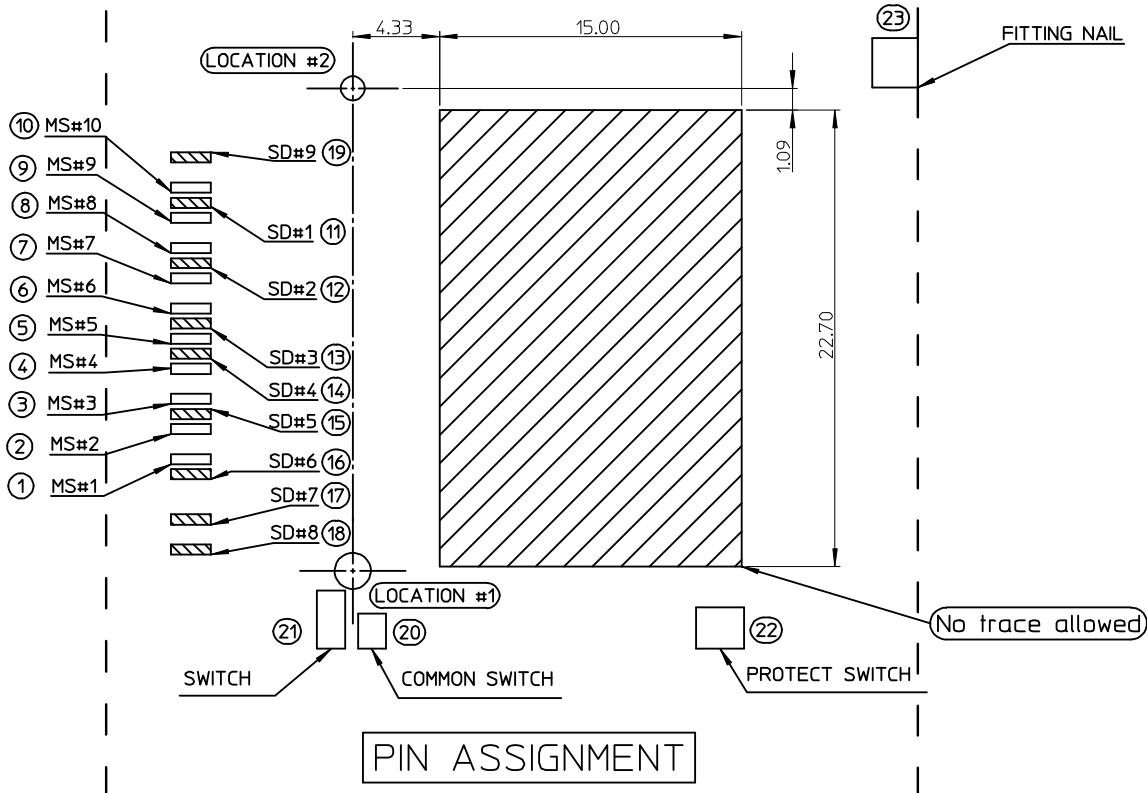
UPDATE DRAWING	EC NO:	2008/08/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	DRWNL:SONG09			mm	INCH	MM ONLY	1:1	METRIC		
D	CHKD:		DESCRIPTION	4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE	
	APPR:			3 PLACES	± ---	± ---	FOX.WU	2003/09/04		
				2 PLACES	± 0.25	± ---	CHECKED BY	DATE	3 IN 1 MEMORY COMBO CONNECTOR PUSH PUSH TYPE	
				1 PLACE	± 0.25	± ---	W.CHANG	2003/09/05		
				ANGULAR ± 3 °			APPROVED BY	DATE	MOLEX INCORPORATED	
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			E.LAN	2003/09/05		
							MATERIAL NO.	DOCUMENT NO.	SHEET NO. 1 OF 5	
							480002001	SD-48000-201		
							THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



FOOT PRINT

RECOMMENDED PCB THICKNESS : 1.0 mm

UPDATE DRAWING EC NO: SH2009-0083 DRW: NLSONG09 2008/08/14 CHKD: APPR:	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION				
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	1 PLACE ± 0.25 ± ---	mm INCH	DRAWN BY FOX.WU	DATE 2003/09/04	TITLE 3 IN 1 MEMORY COMBO CONNECTOR PUSH PUSH TYPE			
		ANGULAR ± 3 °				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		CHECKED BY W. CHANG	DATE 2003/09/05	APPROVED BY E. LAN		DATE 2003/09/05
		MATERIAL NO. 480002001		DOCUMENT NO. SD-48000-201		SHEET NO. 2 OF 5		MOLEX INCORPORATED				



SD CARD CIRCUIT  
 -----  
 WITHOUT CARD  
 #21 SW 0-- --0 #20 GND  
 #22 WP 0-- --0 #20 GND  
 -----  
 CARD INSERTED  
 WRITE PROTECT LOCK  
 #21 SW 0-----0 #20 GND  
 #22 WP 0-- --0 #20 GND  
 -----  
 CARD INSERTED  
 WRITE PROTECT UNLOCK  
 #21 SW 0-----0 #20 GND  
 #22 WP 0-----0 #20 GND

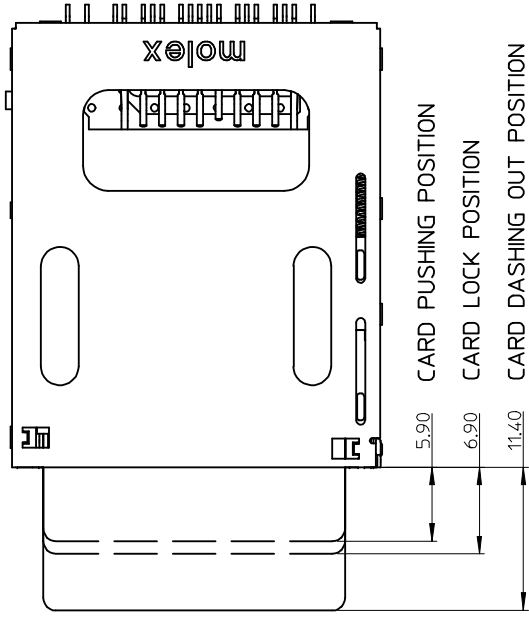
THE SD CARD CONTACTS ARE CONTACTED IN THREE STEPS :  
 1. GROUND VSS (PIN3) AND SUPPLY VOLTAGE VDD (PIN4).  
 2. CLK,CMD,DAT0,DAT1,DAT2 AND VSS (PIN6)  
 3. CD/DAT3 (PIN1)

1	MS-1P (Vss)	15	SD-5P (CLK)
2	MS-2P (BS)	16	SD-6P (Vss)
3	MS-3P (DATA1)	17	SD-7P (DAT0)
4	MS-4P (SDIO/DATA0)	18	SD-8P (DAT1)
5	MS-5P (DATA2)	19	SD-9P (DAT2)
6	MS-6P (INS)	20	SD-SW (GND)
7	MS-7P (DATA3)	21	SW (RSV)
8	MS-8P (SCLK)	22	SD-SW (WP)
9	MS-9P (Vcc)	23	FITTING NAIL
10	MS-10P (Vss)		
11	SD-1P (CD/DAT3)		
12	SD-2P (CMD)		
13	SD-3P (Vss)		
14	SD-4P (Vdd)		

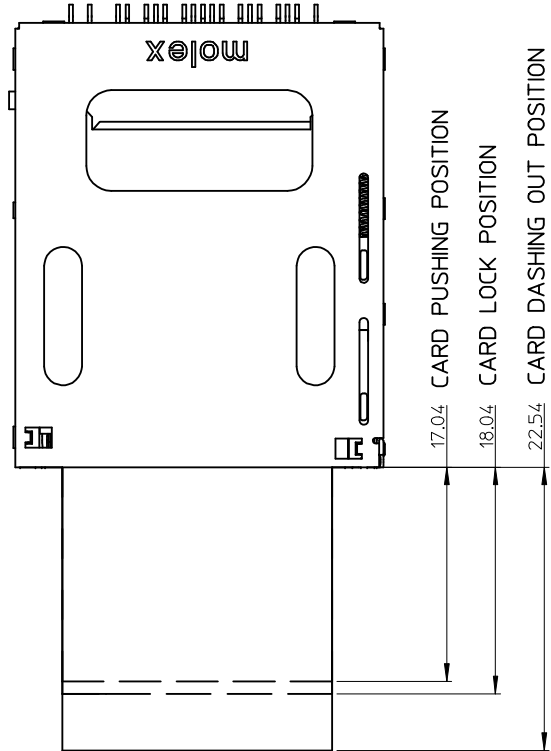
PIN ASSIGNMENT

UPDATE DRAWING EC NO: DRWINL.SONG09 CH'KD: 2008/08/14 APPR:	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▼=0 ▽=0	mm INCH	MM ONLY	1:1	METRIC	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 3 °	DRAWN BY DATE FOX.WU 2003/09/04 CHECKED BY DATE W.CHANG 2003/09/05 APPROVED BY DATE E.LAN 2003/09/05	TITLE	3 IN 1 MEMORY COMBO CONNECTOR PUSH PUSH TYPE	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. DOCUMENT NO. SHEET NO.	MOLEX INCORPORATED		3 OF 5
			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1



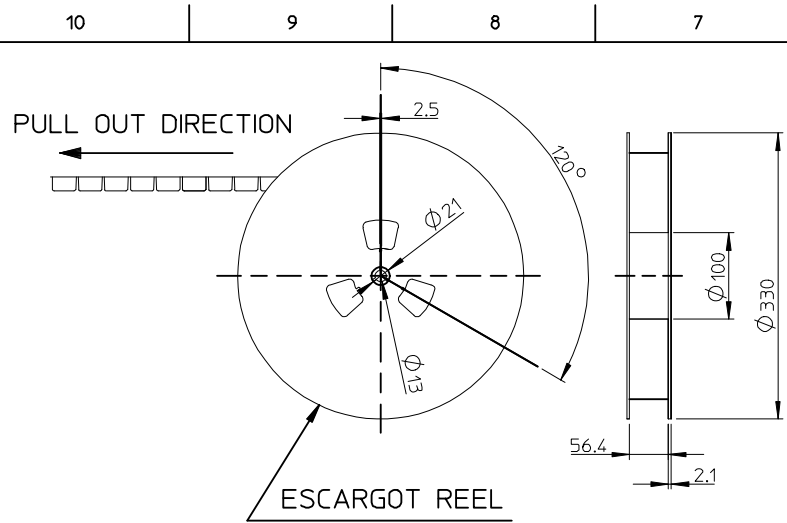
MMC/SD card



MS card

UPDATE DRAWING EC NO: SHZ009-0083 DRWN: LSONG09 2008/08/14 CHKD: APPR:	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.25 ± ---	mm      INCH	DRAWN BY FOX.WU	DATE 2003/09/04	TITLE 3 IN 1 MEMORY COMBO CONNECTOR PUSH PUSH TYPE					
		ANGULAR ± 3 °		CHECKED BY W.CHANG	DATE 2003/09/05						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY E.LAN	DATE 2003/09/05	MATERIAL NO. 480002001		MOLEX INCORPORATED			SHEET NO. 4 OF 5
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

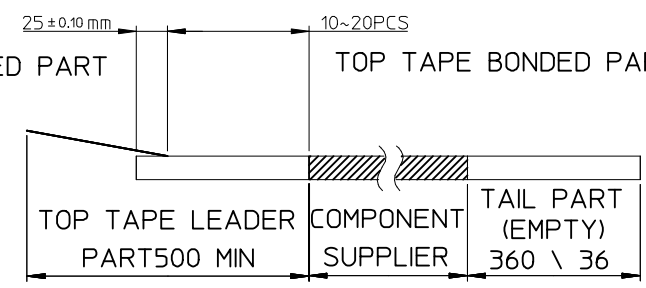


**NOTES**

1. NUMBER OF CONNECTORS: 250 PCS/REEL

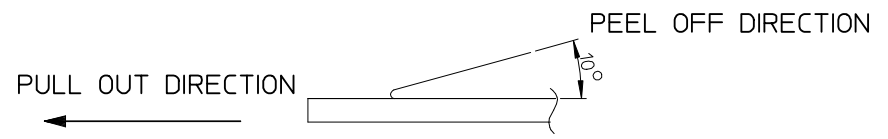
TOP TAPE NON-BONDED PART

TOP TAPE BONDED PART (EMPTY)

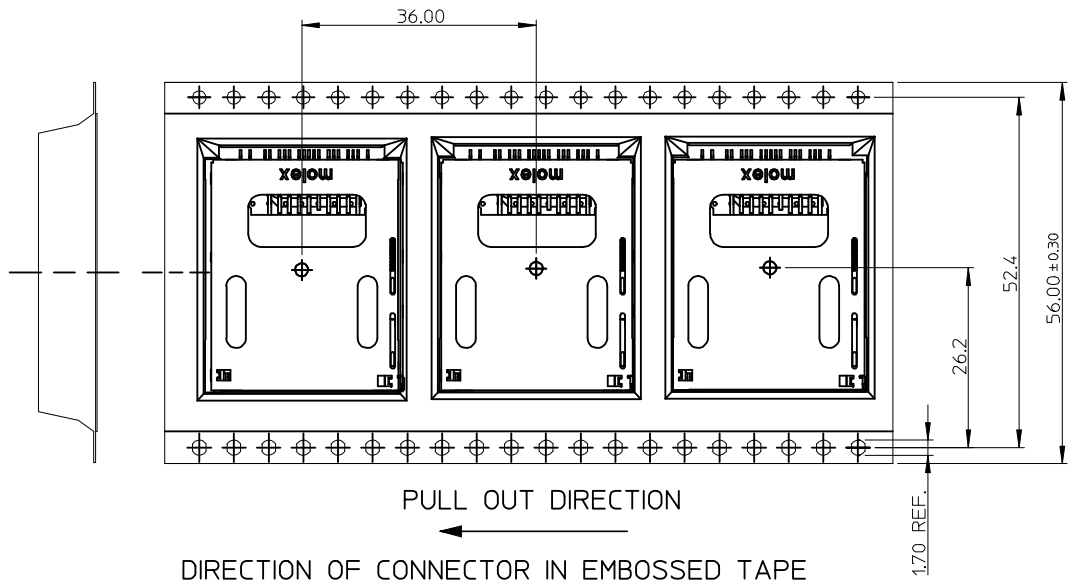


PULL OUT DIRECTION

3. PEEL OFF FORCE OF TOP TAPE: 0.1~1.3 N (10.2~130gf)  
 PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
 (PEEL OFF SPEED: 300mm/min.REF.)



4. PACKAGING DRAWING REFERS TO PK-48000-001



DIRECTION OF CONNECTOR IN EMBOSSED TAPE

UPDATE DRAWING	2008/08/14
EC NO: SH2009-0083	
DRWN: L.SONG	
CHKD: X.J.SONG	
APPR: H.WANG	
REV	DESCRIPTION
D	

QUALITY SYMBOLS	=0
	=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH	
	4 PLACES	± ---	± ---
	3 PLACES	± ---	± ---
	2 PLACES	± 0.25	± ---
	1 PLACE	± 0.25	± ---
ANGULAR ± 3 °			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM ONLY		1:1	METRIC	
DRAWN BY	DATE	TITLE		
FOX.WU	2003/09/04	3 IN 1 MEMORY COMBO CONNECTOR PUSH PUSH TYPE		
CHECKED BY	DATE			
W.CHANG	2003/09/05			
APPROVED BY	DATE	MOLEX INCORPORATED		
E.LAN	2003/09/05			
MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
480002001	SD-48000-201	5 OF 5		